

## LOW DROP POWER SCHOTTKY RECTIFIER

### MAIN PRODUCTS CHARACTERISTICS

$I_{F(AV)}$	2 x 20 A
$V_{RRM}$	45 V
$T_j(\text{max})$	150 °C
$V_F(\text{max})$	0.47 V

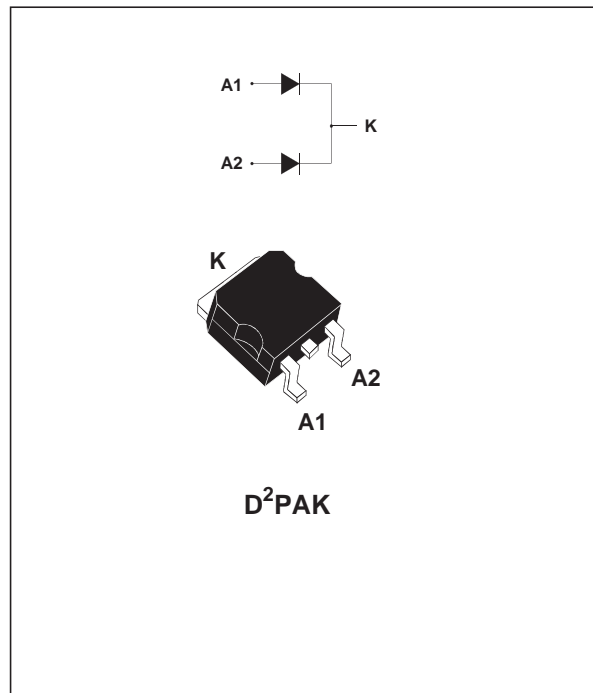
### FEATURES AND BENEFITS

- Very small conduction losses
- Negligible switching losses
- Extremely fast switching
- Low forward voltage drop
- Low thermal resistance

### DESCRIPTION

Dual center tab Schottky rectifier suited for 5V output in off line AC/DC power supplies.

Packaged in D<sup>2</sup>PAK, this device is intended for use in low voltage, high frequency inverters, free-wheeling and polarity protection applications.



### ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter		Value	Unit	
$V_{RRM}$	Repetitive peak reverse voltage		45	V	
$I_{F(RMS)}$	RMS forward current		30	A	
$I_{F(AV)}$	Average forward current	$T_c = 130^\circ\text{C}$	Per diode	20	A
		$\delta = 0.5$	Per device	40	
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10 \text{ ms}$ sinusoidal	220	A	
$I_{RRM}$	Peak repetitive reverse current	$t_p = 2 \mu\text{s}$ square $F = 1\text{kHz}$	1	A	
$T_{stg}$	Storage temperature range		- 65 to + 175	°C	
$T_j$	Maximum operating junction temperature *		150	°C	
$dV/dt$	Critical rate of rise reverse voltage		10000	V/ $\mu\text{s}$	

\* :  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$  thermal runaway condition for a diode on its own heatsink

# STPS41L45CG

## THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case	Per diode	1.5	$^{\circ}\text{C/W}$
		Total	0.8	
$R_{th(c)}$	Coupling		0.1	

When the diodes 1 and 2 are used simultaneously :

$$\Delta T_j(\text{diode 1}) = P(\text{diode 1}) \times R_{th(j-c)}(\text{Per diode}) + P(\text{diode 2}) \times R_{th(c)}$$

## STATIC ELECTRICAL CHARACTERISTICS (per diode)

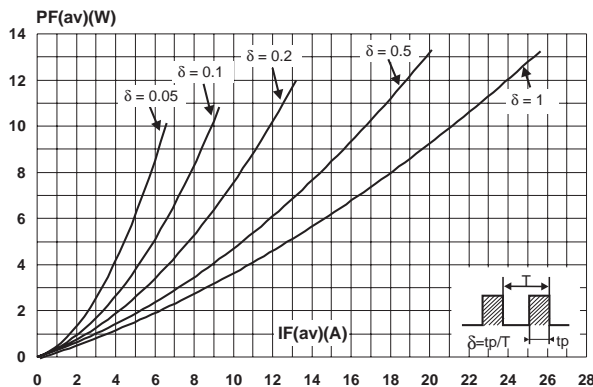
Symbol	Parameter	Tests Conditions		Min.	Typ.	Max.	Unit
$I_R^*$	Reverse leakage current	$T_j = 25^{\circ}\text{C}$	$V_R = V_{RRM}$			1.2	mA
		$T_j = 125^{\circ}\text{C}$			110	220	mA
$V_F^*$	Forward voltage drop	$T_j = 25^{\circ}\text{C}$	$I_F = 20\text{ A}$			0.53	V
		$T_j = 125^{\circ}\text{C}$	$I_F = 20\text{ A}$		0.42	0.47	
		$T_j = 25^{\circ}\text{C}$	$I_F = 40\text{ A}$			0.68	
		$T_j = 125^{\circ}\text{C}$	$I_F = 40\text{ A}$		0.60	0.66	

Pulse test : \*  $t_p = 380\ \mu\text{s}$ ,  $\delta < 2\%$

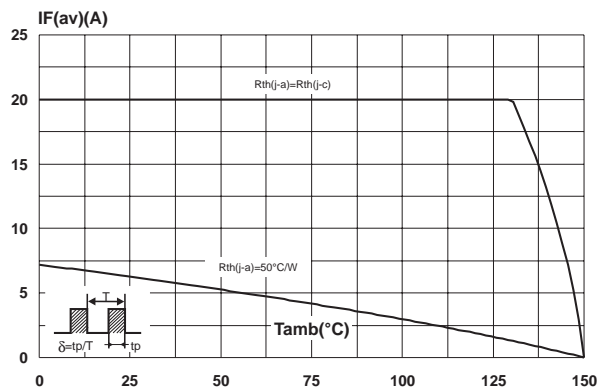
To evaluate the conduction losses use the following equation :

$$P = 0.28 \times I_{F(AV)} + 0.0095 I_{F(RMS)}^2$$

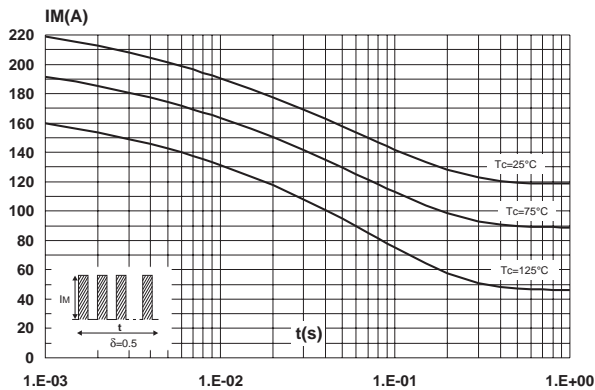
**Fig. 1:** Conduction losses versus average current.



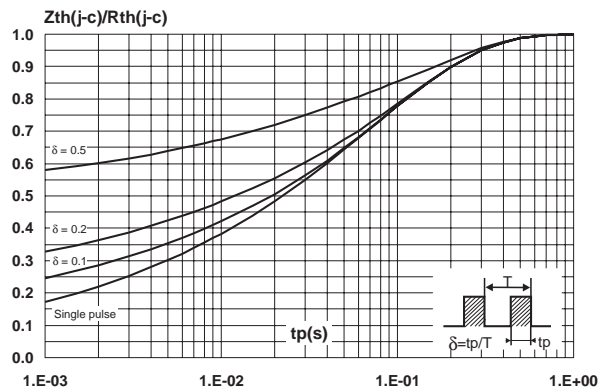
**Fig. 2:** Average forward current versus ambient temperature ( $\delta = 0.5$ ).



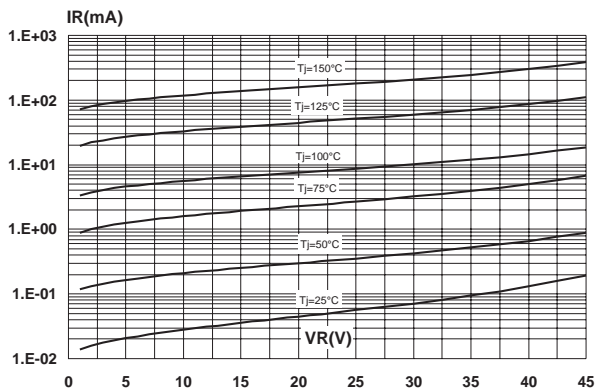
**Fig. 3:** Non repetitive surge peak forward current versus overload duration (maximum values).



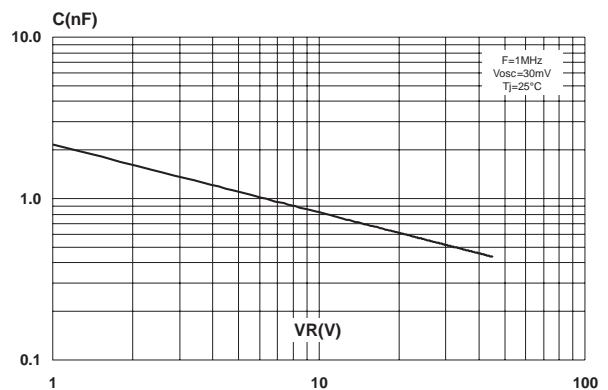
**Fig. 4:** Relative variation of thermal impedance junction to case versus pulse duration.



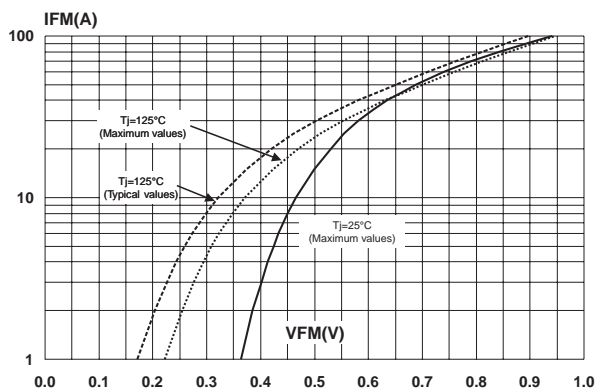
**Fig. 5:** Reverse leakage current versus reverse voltage applied (typical values).



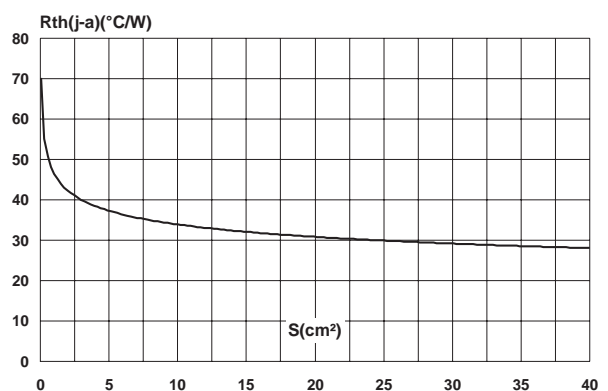
**Fig. 6:** Junction capacitance versus reverse voltage applied (typical values).



**Fig. 7:** Forward voltage drop versus forward current.

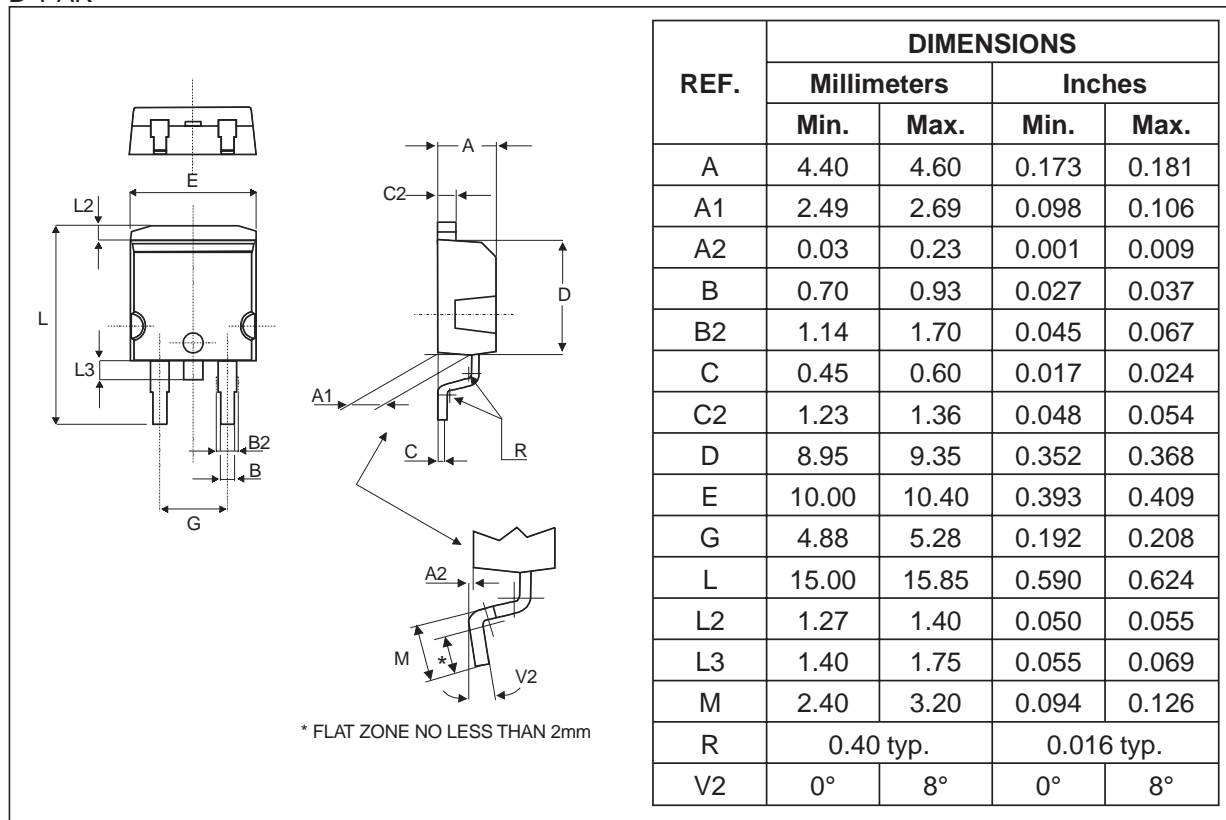


**Fig. 8:** Thermal resistance junction to ambient versus copper surface under tab (epoxy printed board FR4, Cu = 35μm).

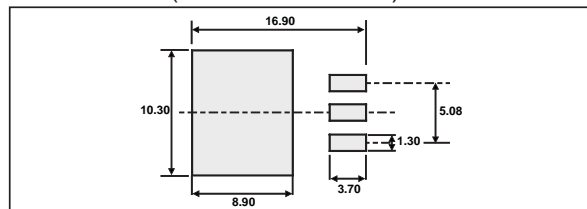


# STPS41L45CG

## PACKAGE MECHANICAL DATA D<sup>2</sup>PAK



### FOOTPRINT (dimensions in mm)



Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS41L45CG	STPS41L45CG	D <sup>2</sup> PAK	1.48 g	50	Tube
STPS41L45CG-TR	STPS41L45CG	D <sup>2</sup> PAK	1.48 g	1000	Tape & reel

- Epoxy meets UL94,V0

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